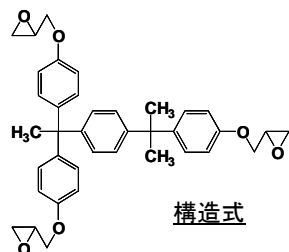


高耐熱3官能エポキシ樹脂 TECHMORE VG3101L

高耐熱・柔軟性（可撓性）・透明持続性のマルチ機能エポキシ樹脂

High heat resistance・Flexibility (flexibility)・Transparent durability multi functional epoxy resin



混合物登録
CAS No. 115254-47-2 90%
CAS No. 180063-56-3 10%

○基本特性/Basic characteristics

Product name	Appearance	Epoxy g/eq	ICI-150℃ Pa.s	Moisture %	Monomer purity %	Total-Cl %	SP °C	Nv %	GHS
VG3101L	solid	205-215	0.12	0.06	80-85	0.1	60	100	
VG3101M80	liquid	205-215	-	-	80-90	0.3	-	80	

○海外法規制登録状況/Overseas regulations

ENCS/日本	TSCA/米国	ECL/韓国	CSNN/台湾	ECSC/中国
○	○	○	○	○

○硬化物性比較/Comparison of cured physical properties

Contents	unit	VG3101	Multi function Epoxy	OCN
TG	°C/DSC	250	247	250
Heat distortion temperature	°C	235	223	235
Flexural strength	Mpa	115	64	76
Flexural modulus	Mpa	2770	2890	3160
Moisture Absorption	%	0.44	-	0.41

Cure conditions

Epoxy/Acid anhydride (酸無水物) = 1.05/1.00 2E4MZ 1% 100℃ 3Hr + 230℃ 2Hr

○VG3101L+Bis-AタイプEpoxyとのブレンド系での硬化物性比較データ

■DICY/ジシアジアミド	VG/Bis-A →	100/0	75/25	50/50	25/75	0/100
Flexural Strength	Mpa	124	131	137	149	151
Flexural Modulus	Mpa	3600	3420	3480	3460	3500
Heat distortion temperature	°C	192	174	153	131	123
■MNA/メチルナジック酸無水物	VG/Bis-A →	100/0	75/25	50/50	25/75	0/100
Flexural Strength	Mpa	120	138	146	140	151
Flexural Modulus	Mpa	2950	3130	3180	3020	3250
Heat distortion temperature	°C	212	203	190	171	170
■DDM/ジアミノジフェニルメタン	VG/Bis-A →	100/0	75/25	50/50	25/75	0/100
Flexural Strength	Mpa	111	109	103	108	110
Flexural Modulus	Mpa	2800	2950	2920	2870	2580
Heat distortion temperature	°C	272	238	213	199	176

上記数値は参考値であり保証するものではありません

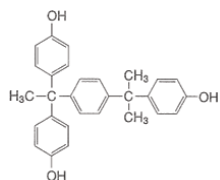
The above values are reference values and there is nothing to guarantee

○Properties of CCL

Condition Press : 190°C 90min Post Cure : 230°C 180min Viscosity of Varmish (Solvent:MEK):40-60mpa · s Catalyst: 2E4MZ 1phr		VG3101	Naphthalene	4-Taminal	Novolac
	g/eq	210	170	200	158-178
	SP	61	95	90	60-72
	Herdener	Phenol Type OH:98-102 SP150-170°C			
TG (TMA)	°C	184	175	170	163
Dk at 1GHz	t0.3	4.2	4.6	4.4	4.4
CTE (23°C-Tg) 0.1X2ply	Ppm/°C	11.8	10.1	12.8	11.9
Flexural strength	Mpa	484	462	404	453
Flexural modulus	Mpa	18150	18340	15350	17620

○Properties of Epoxy Molding Compound

Condition Roll mixing : 100°C Molding temp 180°C Silica 85%wt Lico Wax OP Silane Coupling		VG3101L	Eocn	Naphthalene	DCPD	
	g/eq	209	211	214	257	
	SP	60	66	62	60	
	Herdner	*TP-VG100	Phenol Novolac			
TG(TMA)	°C	200	185	160	153	152
SF	Inch	31	34	30	41	46
Gel Time	Sec	32	44	44	56	65
Melt Torque	N·m	0.35	0.20	0.30	0.25	0.25
Mold Shrinkage	%	0.05	0.10	0.16	0.13	0.16
Absorption	%	0.03	0.04	0.03	0.02	0.02
CTE α1	ppm/°C	15.8	13.4	12.3	11.2	12.1
CTE α2	ppm/°C	48.4	36.0	38.4	38.8	38.5
Flexural strength	Mpa	155	172	193	182	174
Flexural modulus	Mpa	19260	22360	24710	24740	24940



*TP-VG100

mp : 222-225°C
OH : 141
Mw : 424.5
Cas No : 110726-28-8

○取扱注意事項/Handling Precautions

VG3101L

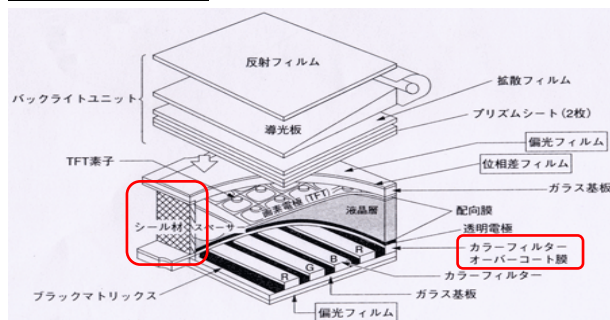
輸送手段 → 夏季 20°C以下の低温輸送
海外輸送手段 → リーファーコンテナ輸送 (20°C以下)
荷姿 紙袋 20KG包装 又は 1KG包装

transportation means → Low temperature transportation in summer below 20 ° C
Overseas transportation means → Reefer container transportation (20 ° C or less)
Packing paper bag 20KG packaging or 1KG packaging

VG3101M80

輸送手段 → 危険品輸送
荷姿 ペール缶又はドラム缶 18KG/200KG 又は 1KG包装
transportation means → Dangerous Goods Transport
Packing 1KG/18KG/200KG

○Application example



樹脂の特長を生かした多くの電子材料の一部に使用されています。
Many electronic materials that make use of the features of resin, It is used for part.

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